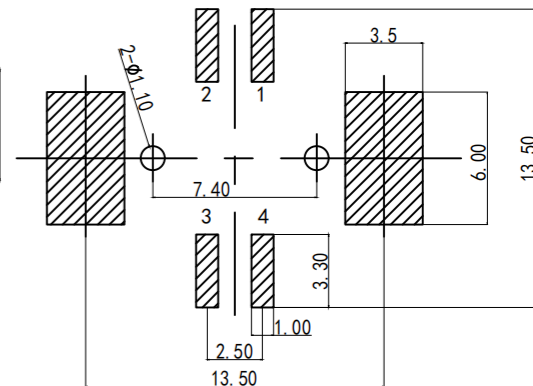
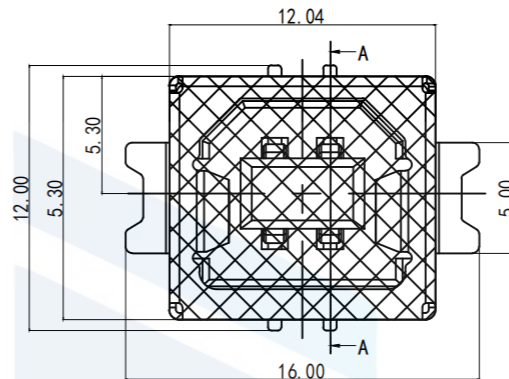
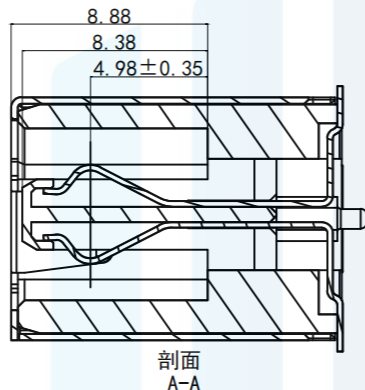
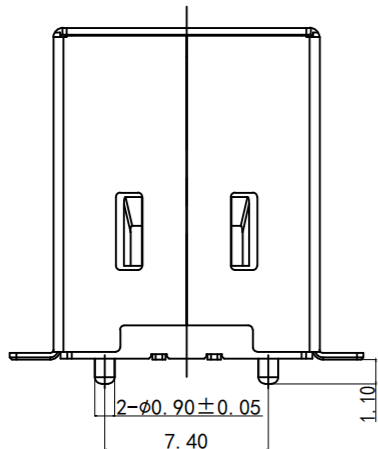
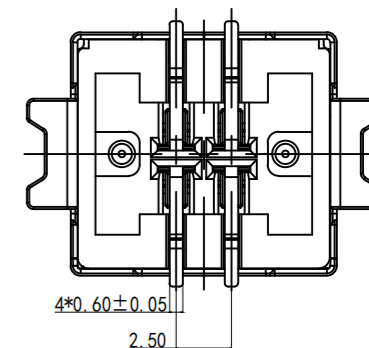
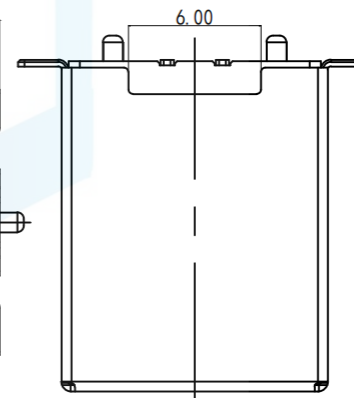
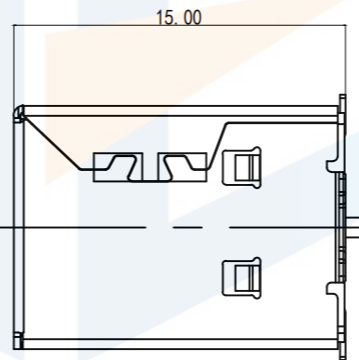


RoHS2.0
Compliant



RECOMMENDED PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCES: ±0.05

PAD AREA



NOTE:

1. Material:

Housing: LCP, Black (Halogen free); Thermoplastics, UL94V-0;

Contact: Copper Alloy

Shell: Copper Alloy

2. FINISH:

Contact: Gold Flash Plated on Contact Area,

80u" Tin Bright Plated on Solder Tails,

50u" Min. Nickel Underplating Over All.

Shell: 50u" Min. Nickel Underplating Over All.

3. Specification:

3.1: Voltage Current Rating: 1.5Amp. 30V/AC

3.2: Electrical:

Insulation Resistance: 100MΩ Min.

Contact Resistance: 20mΩ Max.

Dielectric Withstanding Voltage: 500V/AC 1Minutem

3.3: MECHANICAL

Mating force: 35N Max.

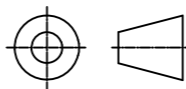
Unmating force: 10N Min.

Durability: 1500 cycles Min.

TOLERANCE

X. XXX	±0.05
X. XX	±0.15
X. X	±0.20
X.	±0.30
ANGLE	±5.0°

PROTECTON



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Dongguan Hengqi Electronic Technology Co., Ltd

<https://www.hq-dz.com>

phone: 15812872448

TITLE:

USB2.0 B母 立式贴片2定位

PART NO: USB2.0-B009

DRAWING NO: 12*12.4*15

DRAWN:

DATE: 18-10-08

UNIT:
mm

CHECKED:

DATE: 18-10-08

SCALE:
FULL

APPROVED:

DATE: 18-10-08

SIZE:
A4